

Appl. No. 10/799,204  
Amdt. Dated March 15, 2006  
Reply to Office action of November 15, 2005

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (currently amended) A method comprising:  
coating a thermally conductive heat spreader body with an organic surface protectant; and  
coupling the heat spreader body directly to a thermal interface material, the thermal  
interface material being in direct contact with an IC integrated circuit (IC) die.
2. (currently amended) A The method ~~as claimed in~~ of claim 1, wherein the coating step  
comprises immersing the heat spreader body in a dipping solution comprising the organic surface  
protectant.
3. (currently amended) A The method ~~as claimed in~~ of claim 1, wherein the organic surface  
protectant comprises one or more triazole compounds and/or salts thereof.
4. (canceled)
5. (currently amended) A The method ~~as claimed in~~ of claim 1, wherein the thermal  
interface material is a solder or solder-polymer hybrid.
6. (currently amended) A The method ~~as claimed in~~ of claim 1, ~~wherein the first further~~  
comprising coating a surface of the heat spreader body is coated with an intervening layer before  
coating with an the organic surface protectant.
7. (currently amended) A The method ~~as claimed in~~ of claim 1, wherein the heat spreader  
body comprises copper.
- 8-23. (canceled)